

P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)		
- 60	0.055 at V _{GS} = - 10 V	- 7.0	30 nC		
- 00	0.065 at V _{GS} = - 4.5 V	- 6.0	30 110		

FEATURES

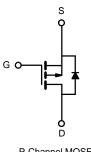
- TrenchFET[®] Power MOSFET
- 100 % UIS Tested

APPLICATIONS

· Load Switch







P-Channel MOSFET

ABSOLUTE MAXIMUM RATING	$\mathbf{S}(1_{A} = 25 \text{ C}, \text{ uniter } \mathbf{S}(1_{A} = 25 \text{ C}, u$;	1	
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 60	v		
Gate-Source Voltage		V _{GS}	± 20	v	
	T _C = 25 °C		- 7.0 ^a		
Continuous Drain Current ($T_1 = 150 \ ^{\circ}C$)	T _C = 70 °C		- 5.2		
Continuous Drain Current $(T_j = 150 \text{ C})$	T _A = 25 °C	I _D	- 4.8 ^b	А	
	T _A = 70 °C		- 4.1 ^b	~	
Pulsed Drain Current	I _{DM}	- 25			
Avalanche Current Pulse	L = 0.1 mH	I _{AS}	- 4.5		
Single Pulse Avalanche Energy	L = 0.1 mm	E _{AS}	10.1	mJ	
Continuous Source-Drain Diode Current	T _C = 25 °C	I _S	6.9 ^a	Α	
Continuous Source-Drain Diode Current	T _A = 25 °C	'S	3.5 ^b	~	
	T _C = 25 °C		10.4 ^a		
Maximum Power Dissipation	T _C = 70 °C	PD	6.6 ^a	w	
	T _A = 25 °C	'D	2.1 ^b	vv	
	T _A = 70 °C		1.1 ^b		
Operating Junction and Storage Temperature R	ange	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^b	Steady State	R _{thJA}	33	40	°C M/	
Maximum Junction-to-Case	Steady State	R _{thJC}	0.98	1.2	°C/W	

Notes:

a. Based on $T_C = 25 \ ^{\circ}C$.

b. Surface mounted on 1" x 1" FR4 board.

SPECIFICATIONS (T _J = 25 °C,	unless othe	erwise noted)				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = -250 \mu A$	- 60			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μΑ		68		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	η = - 200 μΛ		- 5.2		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1.0		- 2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
Zana Osta Malta na Daria Osmani	I _{DSS}	$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1	
Zero Gate Voltage Drain Current		V_{DS} = - 60 V, V_{GS} = 0 V, T_{J} = 55 °C			- 10	μA
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 25			Α
		V _{GS} = - 10 V, I _D = - 3 A		0.055	1 1	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 2 A	0.065			Ω
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 5 A	20			S
Dynamic ^b					•	1
Input Capacitance	C _{iss}			1500		
Output Capacitance	C _{oss}	V _{DS} = - 25 V, V _{GS} = 0 V, f = 1 MHz		200		pF
Reverse Transfer Capacitance	C _{rss}			150		1
Takal Qaka Okazar		V _{DS} = - 30 V, V _{GS} = - 10 V, I _D = - 5 A		38	56	
Total Gate Charge	Qg			19	30	
Gate-Source Charge	Q _{gs}	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -5 \text{ A}$		9		nC
Gate-Drain Charge	Q _{gd}			10		
Gate Resistance	Rg	f = 1 MHz		5.2		Ω
Turn-On Delay Time	t _{d(on)}			10	15	
Rise Time	tr	V_{DD} = - 2 V, R _L = 2 Ω		7	15	
Turn-Off Delay Time	t _{d(off)}	(off) $I_D \cong$ - 5 A, V_{GEN} = - 10 V, R_g = 1 Ω		70	110	ns
Fall Time	t _f			40	60	1
Drain-Source Body Diode Characteristic	s		1	1		
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			- 6.9	•
Pulse Diode Forward Current ^a	I _{SM}				- 15	A
Body Diode Voltage	V _{SD}	I _S = - 3 A		- 1	- 1.5	V
Body Diode Reverse Recovery Time	t _{rr}			45	68	ns
Body Diode Reverse Recovery Charge	Q _{rr}			59	120	nC
Reverse Recovery Fall Time	t _a	I _F = - 5 A, di/dt = 10 A/μs, T _J = 25 °C		29		ns
Reverse Recovery Rise Time	t _b			16		

Notes:

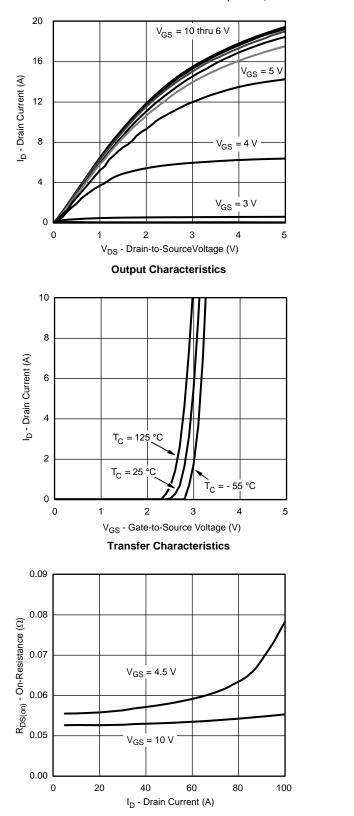
a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

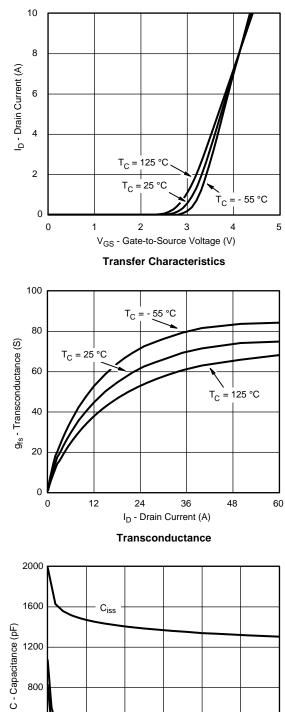
emi

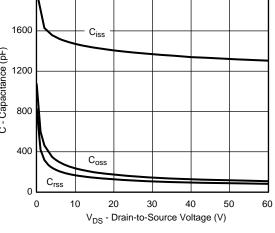




TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

On-Resistance vs. Drain Current

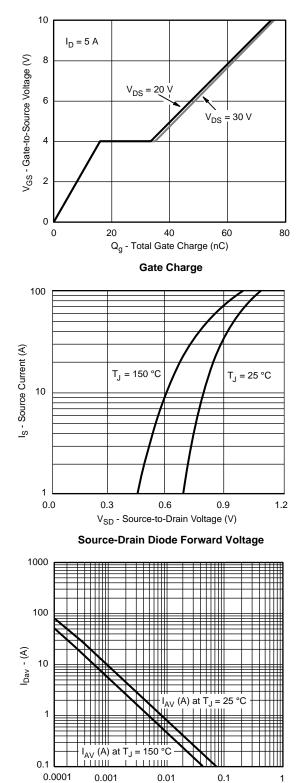




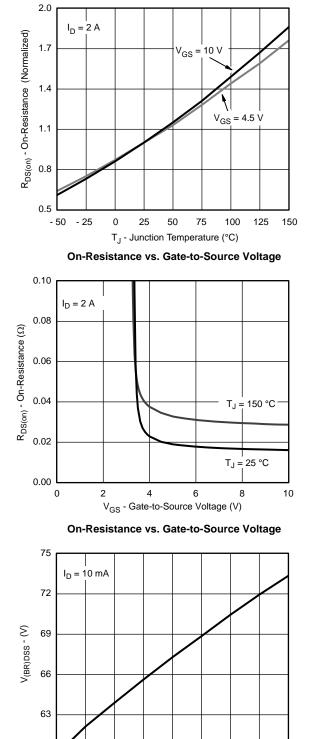
Capacitance



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



T_{in} - (s) Single Pulse Avalanche Current Capability vs. Time

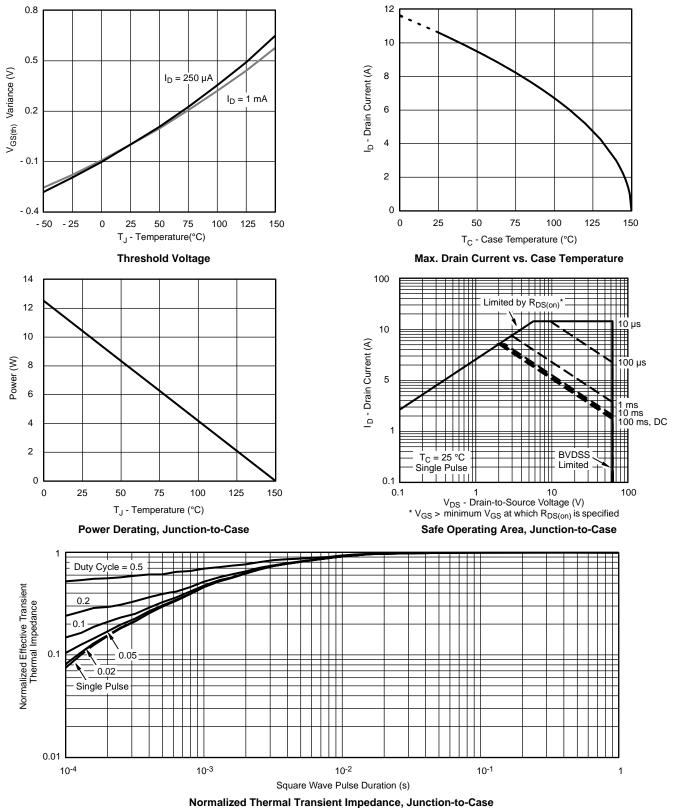


60 - 50 - 25 0 25 50 75 100 125 150 T_J - Temperature (°C)

Drain-Source Breakdown Voltage vs. Junction Temperature

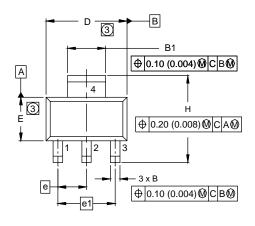


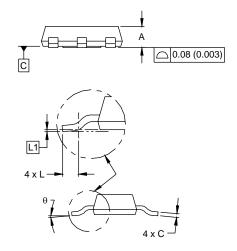
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





SOT-223 (HIGH VOLTAGE)





DIM.	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
А	1.55	1.80	0.061	0.071	
В	0.65	0.85	0.026	0.033	
B1	2.95	3.15	0.116	0.124	
С	0.25	0.35	0.010	0.014	
D	6.30	6.70	0.248	0.264	
E	3.30	3.70	0.130	0.146	
е	2.30 BSC		0.0905 BSC		
e1	4.60 BSC		0.181 BSC		
Н	6.71	7.29	0.264	0.287	
L	0.91	-	0.036	-	
L1	0.061 BSC		0.0024 BSC		
θ	-	10'	-	10'	

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.

2. Dimensions are shown in millimeters (inches).

3. Dimension do not include mold flash.

4. Outline conforms to JEDEC outline TO-261AA.



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